

DCAH0S04

Dielectric Chip Antenna (3.05x1.6x0.55 mm)



This specification covers the 802.11a/b/g/n

Product Specifications

Working Frequency: 2400~2500MHz ; 5150~5825MHz

Dimension: 3.05×1.6×0.55 mm

VSWR: 2.0 ; 2.0

Peak Gain: 1dBi (typ) ; 2.5 dBi (typ)

Efficiency(peak): 75% ; 80%

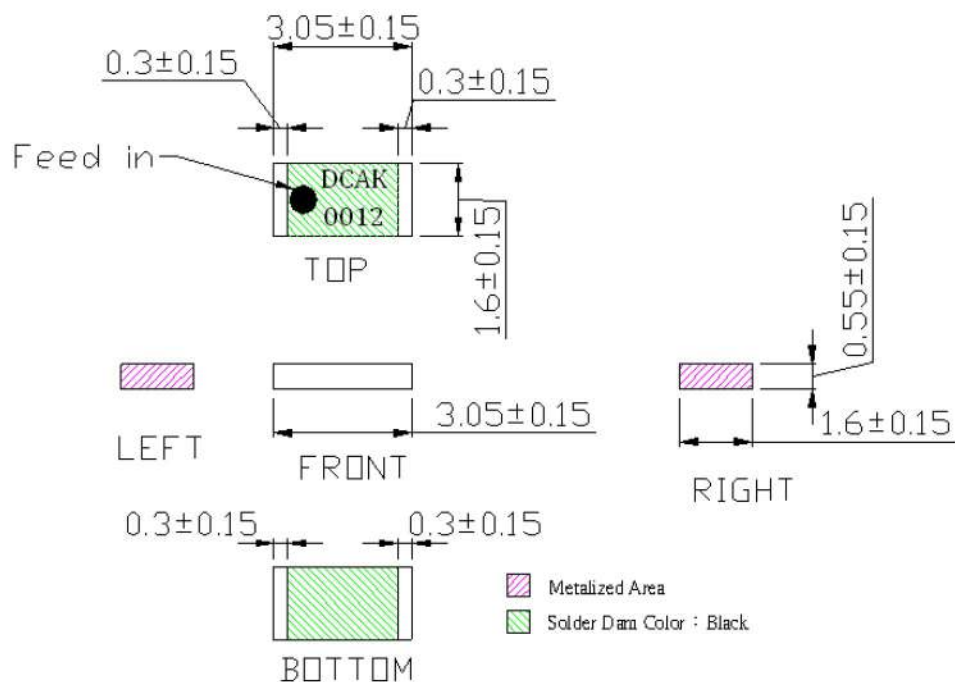
Polarization: Linear

Impedance: 50 Ω

Operating Temperature: -40~85°C

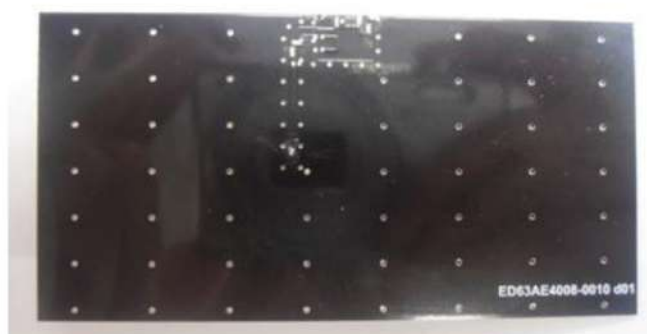
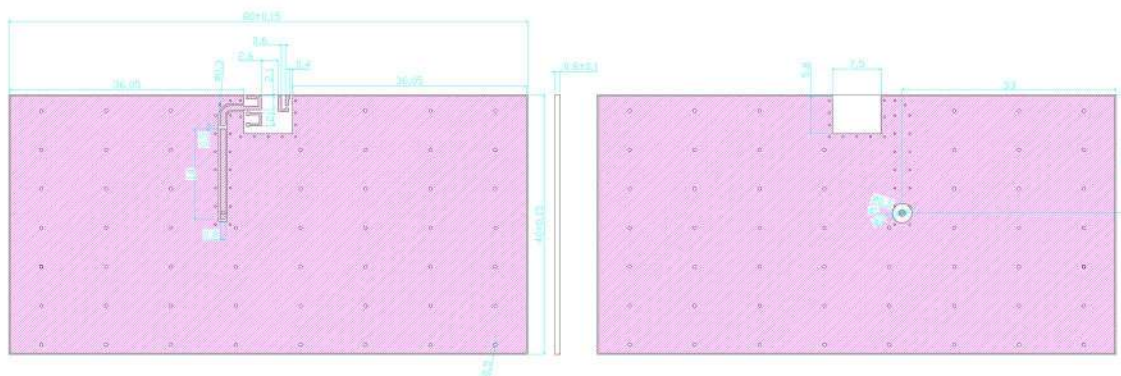
Antenna

Antenna Dimensions

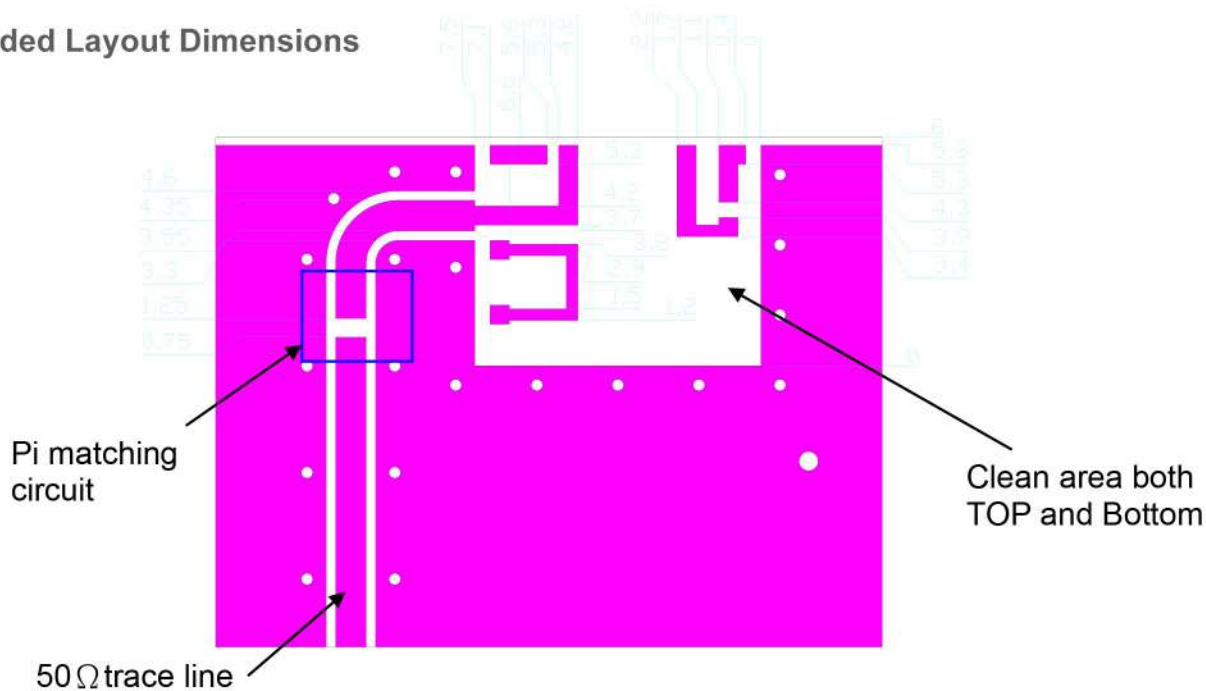


Unit: mm

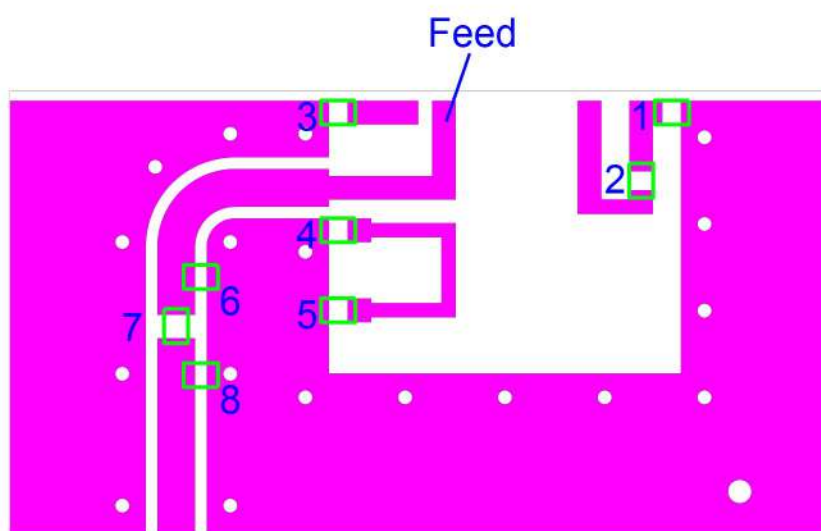
Board Demo Dimension



Recommended Layout Dimensions

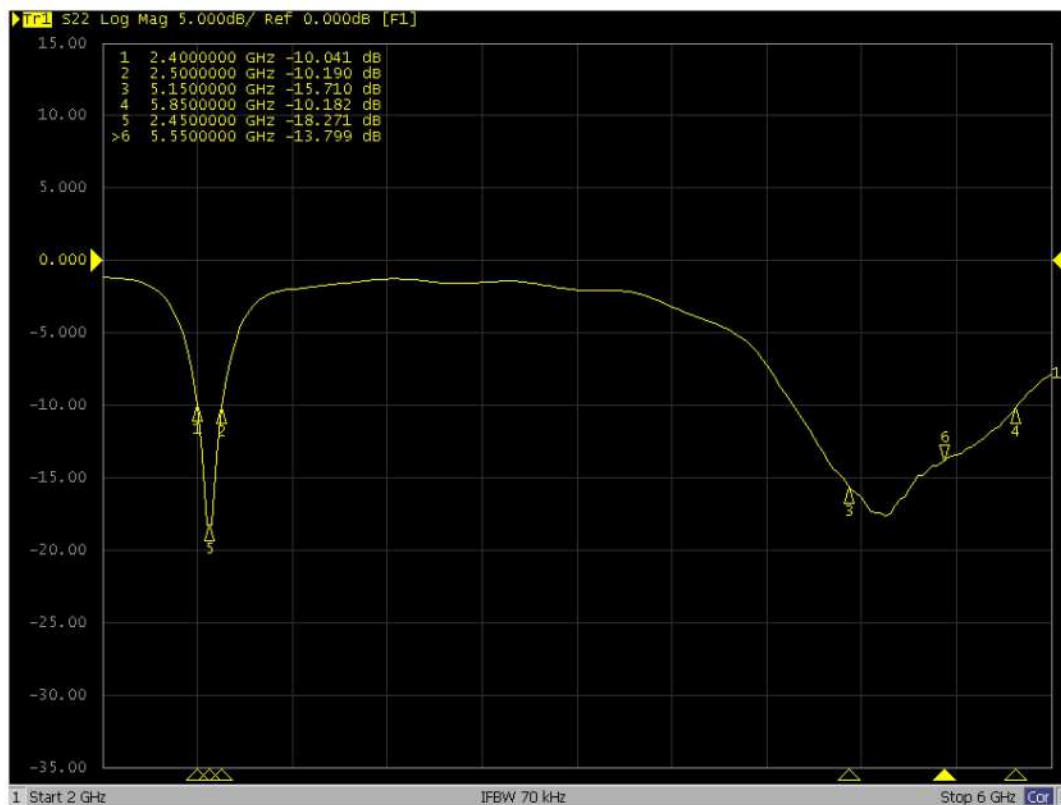


Matching Circuit



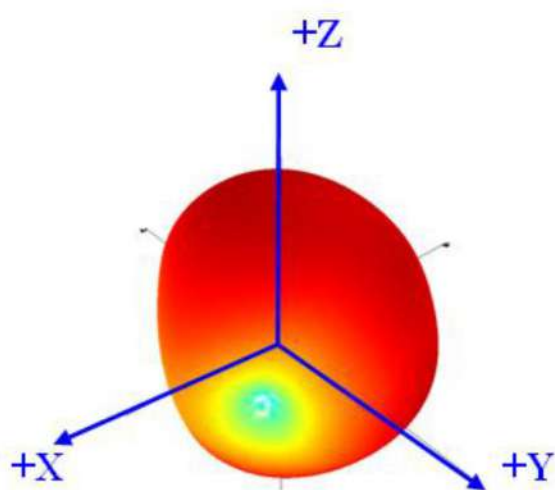
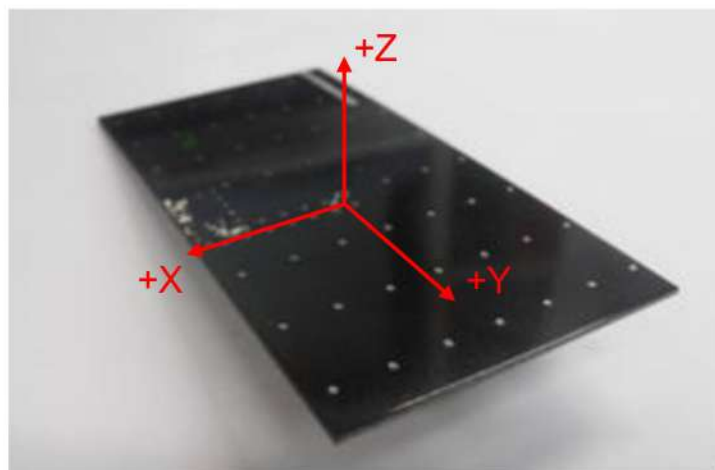
Matching Circuit Component								
NO.	1	2	3	4	5	6	7	8
Description	1.2pF	1pF	N.A	N.A	N.A	1.2nH	1nH	N.A

Return Loss

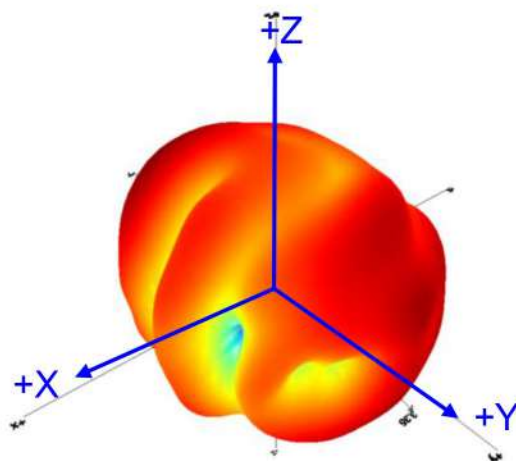


Return Loss	2400MHz	2450MHz	2500MHz	5150MHz	5550MHz	5850MHz
S11	-10.04	-18.27	-10.19	-15.71	-13.79	-10.18

3D Pattern



@2450MHz

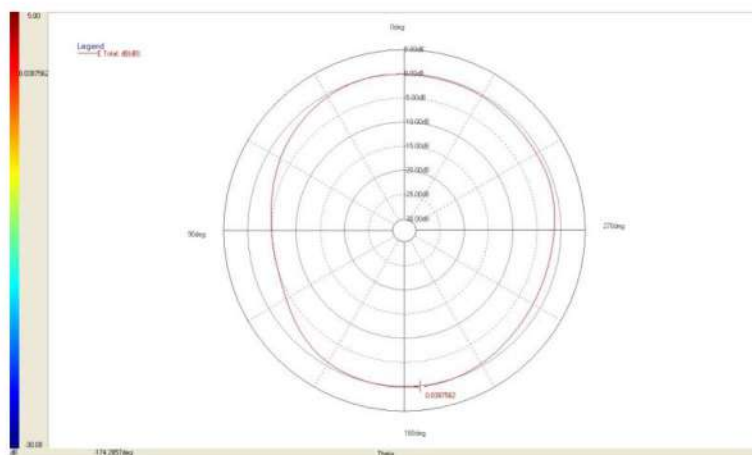


@5550MHz

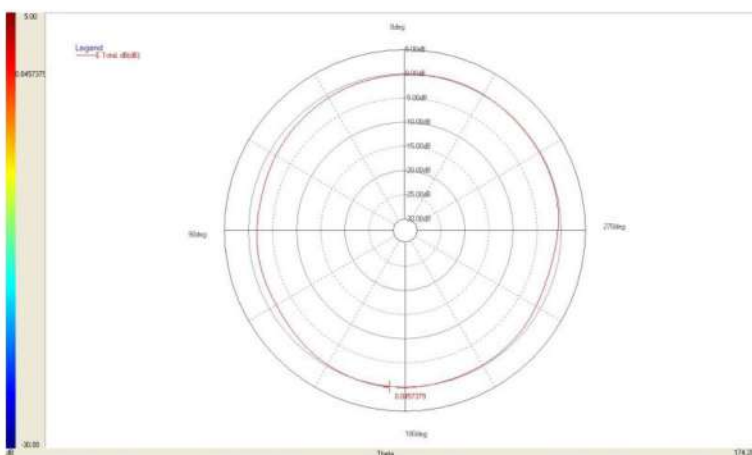
Electrical Performance

2D Radiation Pattern

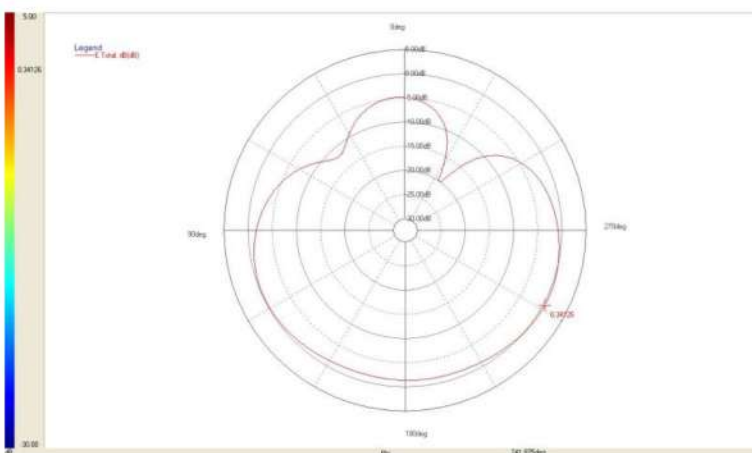
XZ-Plane 2450MHz



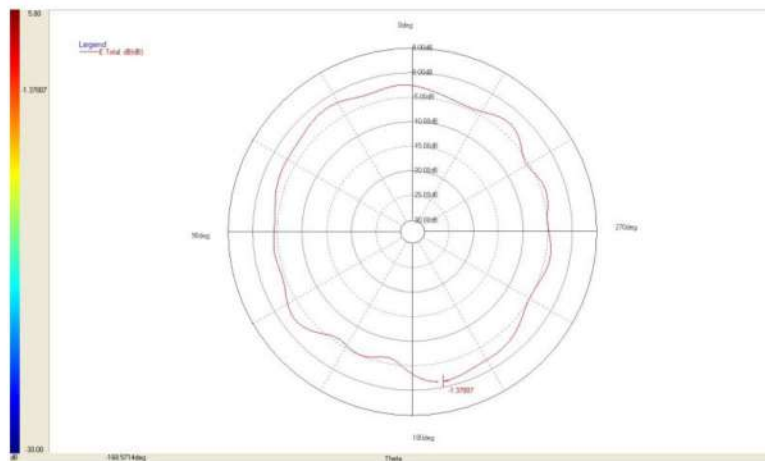
YZ-Plane 2450MHz



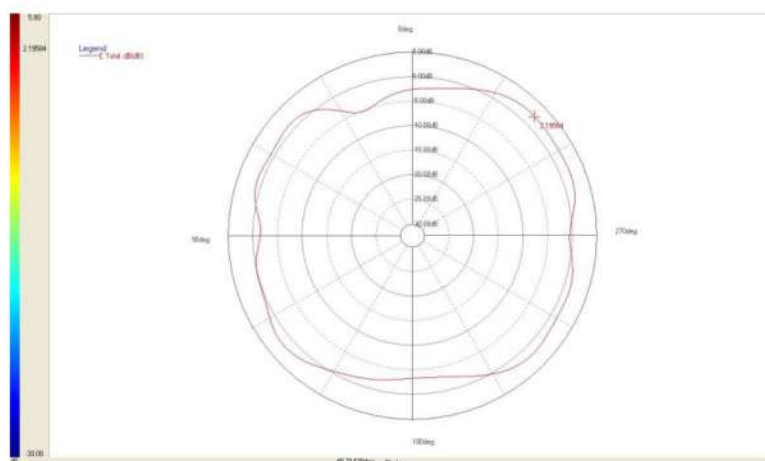
XY-Plane 2450MHz



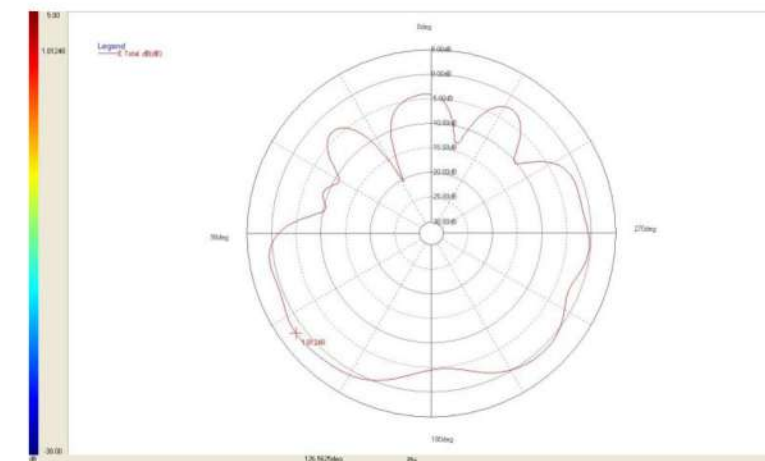
XZ-Plane 5550MHz



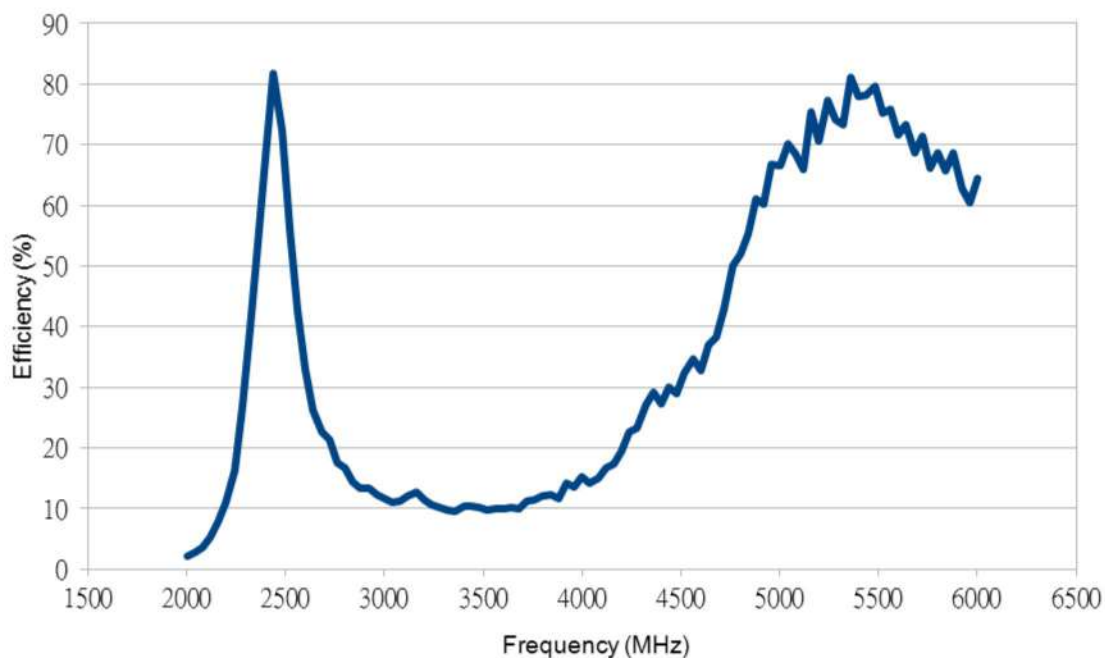
YZ-Plane 5550MHz



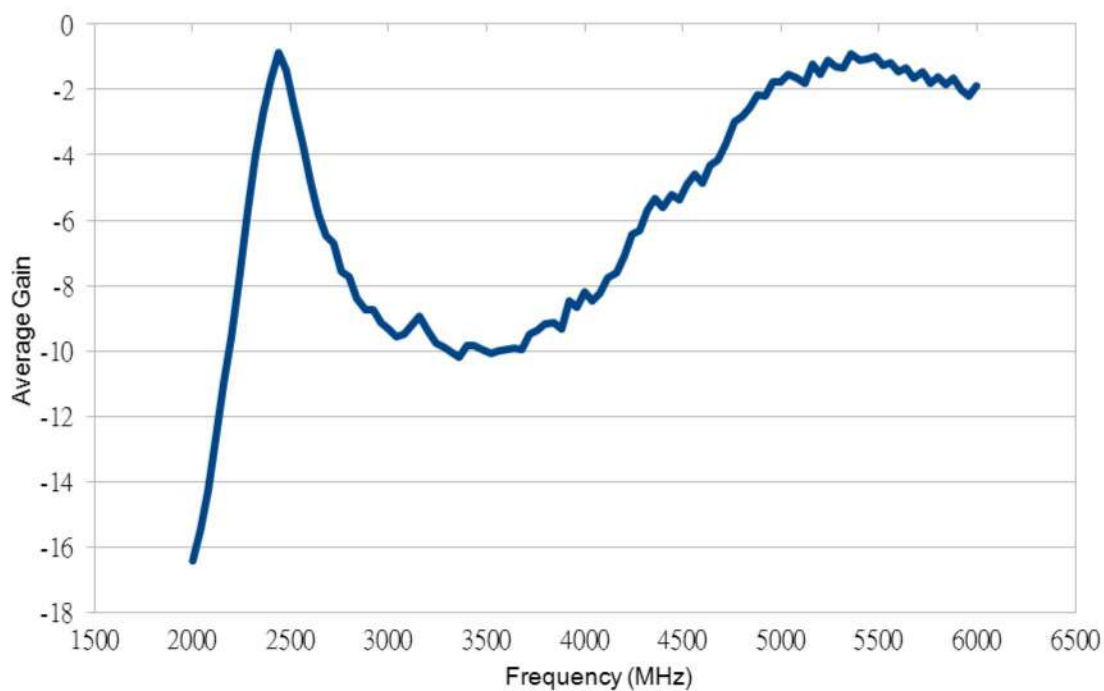
XY-Plane 5550MHz



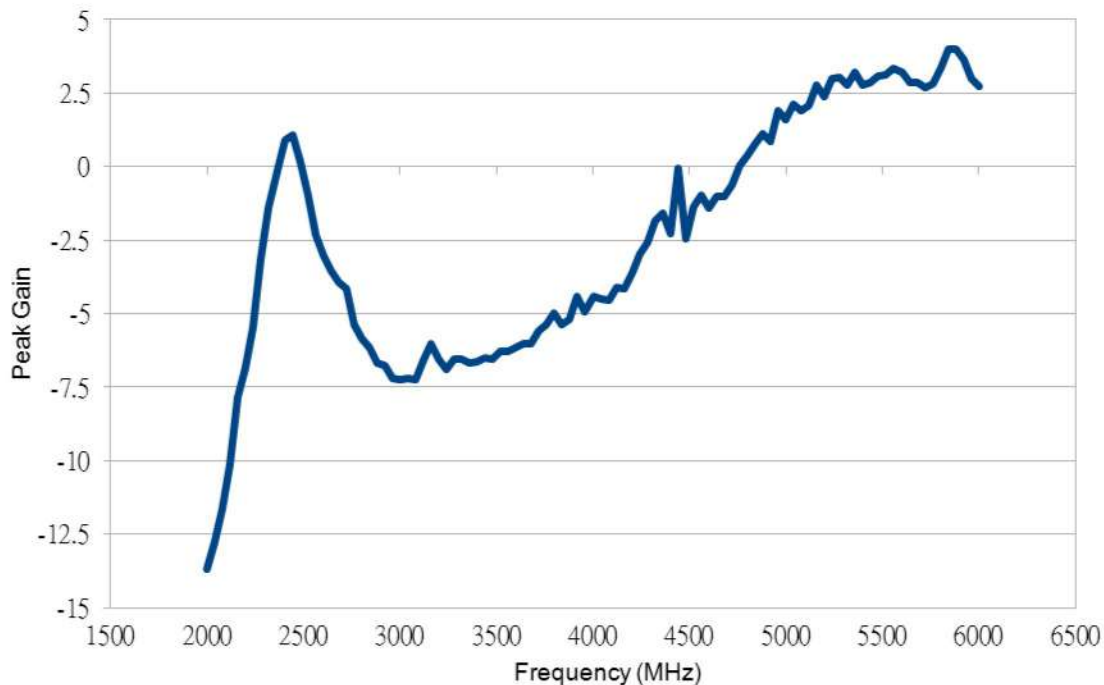
Efficiency



Average Gain



Peak Gain



WLAN	2400MHz	2450MHz	2500MHz	5150MHz	5850MHz
Efficiency(%)	68.02	79.73	65.16	75.38	65.62
Average	-1.67	-0.98	-1.86	-1.22	-1.82
Peak	0.88	1.05	-0.19	2.56	4.01

Environmental Conditions

Operating conditions

The antenna has the electrical characteristics given in Tables 1 in the temperature range of -40°C to $+85^{\circ}\text{C}$ and under the environmental conditions of $+40^{\circ}\text{C}$ and 0-95% relative humidity.

Storage temperature range

The storage temperature range of product is -40°C to $+85^{\circ}\text{C}$.

Reliability Tests

Low-temperature test

Expose the specimen to -40°C for 500 hours and then to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

High-temperature test

Expose the specimen to $+85^{\circ}\text{C}$ for 500 hours and then to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

High-temperature/high-humidity test

Subject the object to the environmental conditions of $+85^{\circ}\text{C}$ and 90-95% relative humidity for 96 hours, then expose it to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

Thermal shock test

Subject the object to cyclic temperature change (-40°C , 30 minutes \leftrightarrow $+85^{\circ}\text{C}$, 30 minutes) for 5 cycles, then expose to normal temperature/humidity for 24 hours or more.

Vibration test

Sinusoidal vibration test

Subject the object to vibrations of 5 to 200 to 5Hz swept in 10 minutes, 4.5G a maximum (2mm amplitude), in X and Y directions for two hours each and in Z direction for four hours. After this test, examine its appearance functions.

Vibration test in packaged condition

Subject the object, which is packaged as illustrated, to vibrations of 15 to 60 to 15Hz swept in 6 minutes, 4G at maximum (2mm amplitude at maximum) applied in X, Y and Z directions for two hours each, i.e. six hours in total. After this test, examine its appearance and functions.

Free fall test in packaged condition

Drop the object, which is packaged as illustrated, to a concrete surface from the height of 90 cm, on one corner, three edges and six faces once each, i.e. 10 times in total. After this test, examine its appearance and functions.

Soldering heat resistance test

The lead pins of the unit are soaked in solder bath at $260 \pm 5^{\circ}\text{C}$ for 10 seconds.

After this test, examine its appearance and functions.

Adhesion test

The device is subjected to be soldered on test PCB. Then apply 0.5Kg (5N) of force for 5 ± 1 seconds in the direction of parallel to the substrate. (The soldering should be done by reflow and be conducted with care so that the soldering is uniform and free of defect by stress such as heat shock).

Warranty

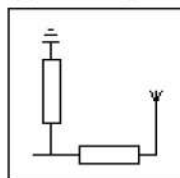
If any defect occurs from the product during proper use within a year after delivery, it will be repaired or replaced free of charge.

Other

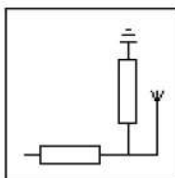
Any question arising from this specification manual shall be solved by arrangement made by both parties.

Transmission Line and Matching

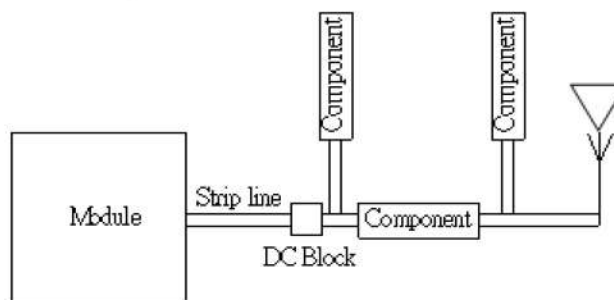
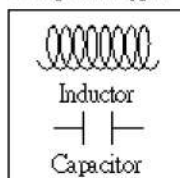
Typical config.1



Typical config.2



Component types



The matching network has to be individually designed using one, two or three components.

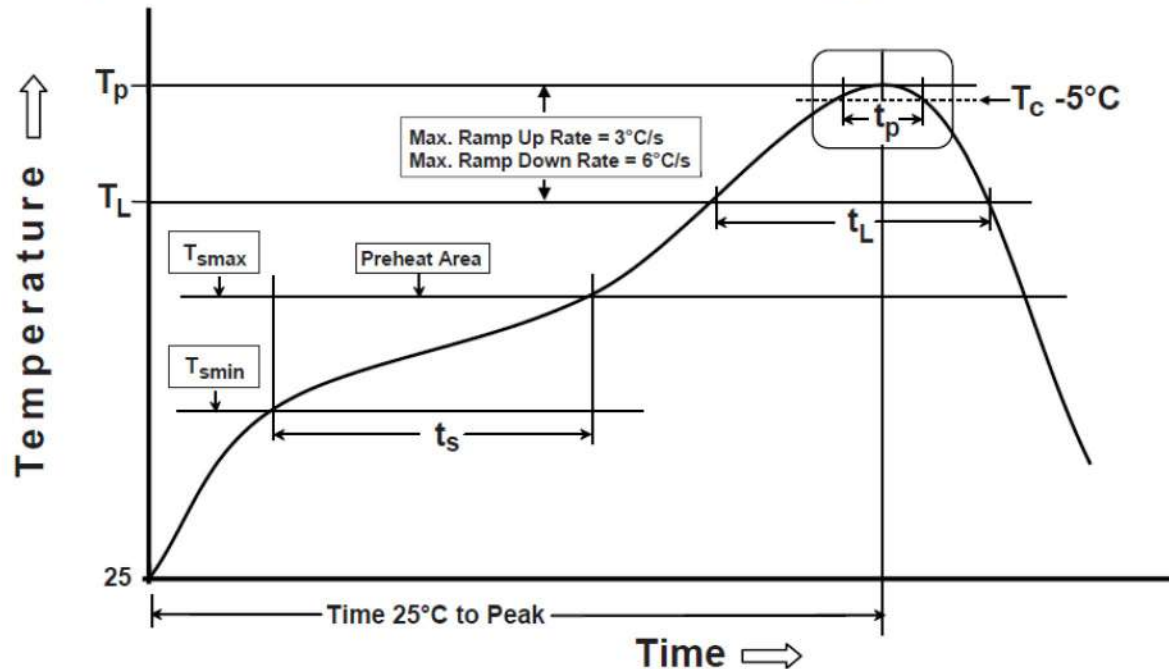
Recommended Reflow Soldering Profile

Cirocomm products can be assembled following Pb-free assembly. According to the Standard **IPC/JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 5-10 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note : All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

Soldering condition : Soldering iron temperature 270 ± 10 °C.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature 270 ± 10 °C or 3 seconds, it will make component surface peeling or damage. Soldering iron can not leakage of electricity.